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Product Termination Notification

Product Group: SIL/Thursday February 19, 2026/PTN-SIL-013-2026-REV-0



Conversion to Copper (Cu) Wire – SQ4532AEY

For further information, please contact your regional Vishay office.

CONTACT INFORMATION

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Description of Change: The affected part number listed in this notification will be converted from gold (Au) bond wire to a copper (Cu) wire material set. The new ordering code is SQ4532CEY-T1_GE3 which has identical silicon technology and silicon die design as SQ4532AEY. Small changes to the data sheet AC parameters are a consequence of lot to lot variation and/or updated characterization methods and some specifications are improved without negative impact (reference: SQ4532CEY Doc # 61727 Rev. A). Device performance in the application will not be impacted. There will be no change to the wafer fab location.

Reason for Change: Standardization of materials

Expected Influence on Quality/Reliability/Performance: None

Part Numbers/Series/Families Affected: SQ4532AEY-T1_GE3, SQ4532AEY-T1_BE3,

Vishay Brand(S): Vishay Siliconix

Time Schedule:

Last Time Buy Date: Sunday August 23, 2026

Last Time Ship Date: Monday February 22, 2027

Sample Availability: Qualified samples of replacement product are available on request.

Product Identification: SQ4532CEY-T1_GE3

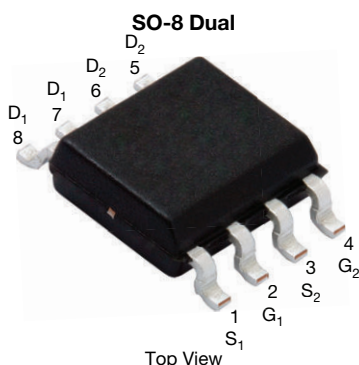
Qualification Data: AEC Q101 qualification data of replacement product is available. Qualification PPAP is available on request.

This PTN is considered approved, without further notification, unless we receive specific customer concerns before Sunday July 26, 2026 or as specified by contract.

Issued By: Lance Gurrola, automostechsupport@vishay.com



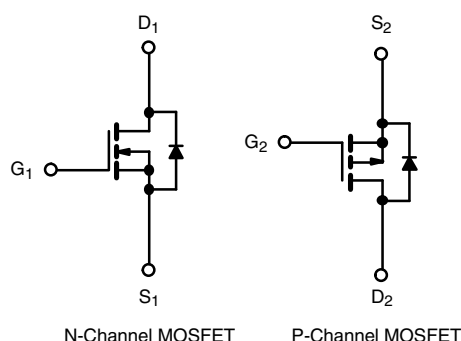
Automotive N-and P-Channel 30 V (D-S) 175 °C MOSFET



Marking Code: Q4532C

FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified °
- 100 % R_g and UIS tested
- Material categorization:
for definitions of compliance please see
www.vishay.com/doc?99912

RoHS
COMPLIANT
HALOGEN
FREE

PRODUCT SUMMARY		
	N-CHANNEL	P-CHANNEL
V _{DS} (V)	30	-30
R _{DS(on)} (Ω) at V _{GS} = ± 10 V	0.031	0.070
R _{DS(on)} (Ω) at V _{GS} = ± 4.5 V	0.042	0.190
I _D (A)	7.3	-5.3
Configuration	N- and p-pair	

ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and halogen-free	SQ4532CEY (for detailed order number please see www.vishay.com/doc?79771)

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	N-CHANNEL	P-CHANNEL	UNIT
Drain-source voltage			V _{DS}	30	-30	V
Gate-source voltage			V _{GS}	± 20		
Continuous drain current	T _C = 25 °C		I _D	7.3	-5.3	A
	T _C = 125 °C			4.2	-3	
Continuous source current (diode conduction)			I _S	4.2	-3	
Pulsed drain current ^a			I _{DM}	29	-21	
Single pulse avalanche current	L = 0.1 mH		I _{AS}	10	-9	mJ
Single pulse avalanche energy			E _{AS}	5	4	
Maximum power dissipation ^a	T _C = 25 °C		P _D	3.3	3.3	W
	T _C = 125 °C			1.1	1.1	
Operating junction and storage temperature range			T _J , T _{std}	-55 to +175		°C

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	N-CHANNEL	P-CHANNEL	UNIT
Junction-to-ambient	R _{thJA}	110	105	°C/W
Junction-to-foot (drain)	R _{thJF}	45	45	

Notes

- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %
- When mounted on 1" square PCB (FR4 material)
- Parametric verification ongoing



SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)									
PARAMETER		SYMBOL	TEST CONDITIONS			MIN.	TYP.	MAX.	UNIT
Static									
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0, I _D = 250 μA		N-Ch	30	-	-	V	
		V _{GS} = 0, I _D = -250 μA		P-Ch	-30	-	-		
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		N-Ch	1.5	2	2.5		
		V _{DS} = V _{GS} , I _D = -250 μA		P-Ch	-1.5	-2	-2.5		
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V		N-Ch	-	-	± 100	nA	
				P-Ch	-	-	± 100		
Zero gate voltage drain current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 30 V	N-Ch	-	-	1	μA	
		V _{GS} = 0 V	V _{DS} = -30 V	P-Ch	-	-	-1		
		V _{GS} = 0 V	V _{DS} = 30 V, T _J = 125 °C	N-Ch	-	-	50		
		V _{GS} = 0 V	V _{DS} = -30 V, T _J = 125 °C	P-Ch	-	-	-50		
		V _{GS} = 0 V	V _{DS} = 30 V, T _J = 175 °C	N-Ch	-	-	150		
		V _{GS} = 0 V	V _{DS} = -30 V, T _J = 175 °C	P-Ch	-	-	-150		
On-state drain current ^a	I _{D(on)}	V _{GS} = 10 V	V _{DS} = 5 V	N-Ch	15	-	-	A	
		V _{GS} = -10 V	V _{DS} = -5 V	P-Ch	-15	-	-		
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.9 A	N-Ch	-	0.021	0.031	Ω	
		V _{GS} = -10 V	I _D = -2.5 A	P-Ch	-	0.056	0.070		
		V _{GS} = 10 V	I _D = 3.9 A, T _J = 125 °C	N-Ch	-	-	0.064		
		V _{GS} = -10 V	I _D = -2.5 A, T _J = 125 °C	P-Ch	-	-	0.100		
		V _{GS} = 10 V	I _D = 3.9 A, T _J = 175 °C	N-Ch	-	-	0.082		
		V _{GS} = -10 V	I _D = -2.5 A, T _J = 175 °C	P-Ch	-	-	0.117		
		V _{GS} = 4.5 V	I _D = 3.1 A	N-Ch	-	0.033	0.042		
		V _{GS} = -4.5 V	I _D = -1.8 A	P-Ch	-	0.157	0.190		
Forward transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 3.5 A		N-Ch	-	22	-	S	
		V _{DS} = -15 V, I _D = -4.0 A		P-Ch	-	5.5	-		
Dynamic ^b									
Input capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = 15 V, f = 1 MHz	N-Ch	-	357	535	pF	
		V _{GS} = 0 V	V _{DS} = -15 V, f = 1 MHz	P-Ch	-	352	528		
Output capacitance	C _{oss}	V _{GS} = 0 V	V _{DS} = 15 V, f = 1 MHz	N-Ch	-	82	123		
		V _{GS} = 0 V	V _{DS} = -15 V, f = 1 MHz	P-Ch	-	95	142		
Reverse transfer capacitance	C _{rss}	V _{GS} = 0 V	V _{DS} = 15 V, f = 1 MHz	N-Ch	-	36	53		
		V _{GS} = 0 V	V _{DS} = -15 V, f = 1 MHz	P-Ch	-	59	88		
Total gate charge	Q _g	V _{GS} = 10 V	V _{DS} = 15 V, I _D = 3.9 A	N-Ch	-	5.9	7.8	nC	
		V _{GS} = -10 V	V _{DS} = -15 V, I _D = -2.5 A	P-Ch	-	7.9	10.2		
Gate-source charge	Q _{gs}	V _{GS} = 10 V	V _{DS} = 15 V, I _D = 3.9 A	N-Ch	-	1	-		
		V _{GS} = -10 V	V _{DS} = -15 V, I _D = -2.5 A	P-Ch	-	1.1	-		
Gate-drain charge ^c	Q _{gd}	V _{GS} = 10 V	V _{DS} = 15 V, I _D = 3.9 A	N-Ch	-	1.9	-		
		V _{GS} = -10 V	V _{DS} = -15 V, I _D = -2.5 A	P-Ch	-	2.7	-		
Gate resistance	R _g	f = 1 MHz		N-Ch	1.7	3.4	5.1	Ω	
				P-Ch	2.8	5.8	8.6		



SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Turn-on delay time	t _{d(on)}	V _{DD} = 15 V, R _L = 15 Ω I _D ≡ 1 A, V _{GEN} = 10 V, R _g = 1 Ω	N-Ch	-	6	9	ns
		V _{DD} = -15 V, R _L = 15 Ω I _D ≡ -1 A, V _{GEN} = -10 V, R _g = 1 Ω	P-Ch	-	7	11	
Rise time	t _r	V _{DD} = 15 V, R _L = 15 Ω I _D ≡ 1 A, V _{GEN} = 10 V, R _g = 1 Ω	N-Ch	-	3	6	
		V _{DD} = -15 V, R _L = 15 Ω I _D ≡ -1 A, V _{GEN} = -10 V, R _g = 1 Ω	P-Ch	-	4	8	
Turn-off delay time	t _{d(off)}	V _{DD} = 15 V, R _L = 15 Ω I _D ≡ 1 A, V _{GEN} = 10 V, R _g = 1 Ω	N-Ch	-	15	23	
		V _{DD} = -15 V, R _L = 15 Ω I _D ≡ -1 A, V _{GEN} = -10 V, R _g = 1 Ω	P-Ch	-	19	29	
Fall time	t _f	V _{DD} = 15 V, R _L = 15 Ω I _D ≡ 1 A, V _{GEN} = 10 V, R _g = 1 Ω	N-Ch	-	2	4	
		V _{DD} = -15 V, R _L = 15 Ω I _D ≡ -1 A, V _{GEN} = -10 V, R _g = 1 Ω	P-Ch	-	4	8	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed current ^a	I _{SM}		N-Ch	-	-	29	A
			P-Ch	-	-	-21	
Forward voltage	V _{SD}	I _S = 2 A	N-Ch	-	0.8	1.2	V
		I _S = -1.5 A	P-Ch	-	-0.8	-1.2	

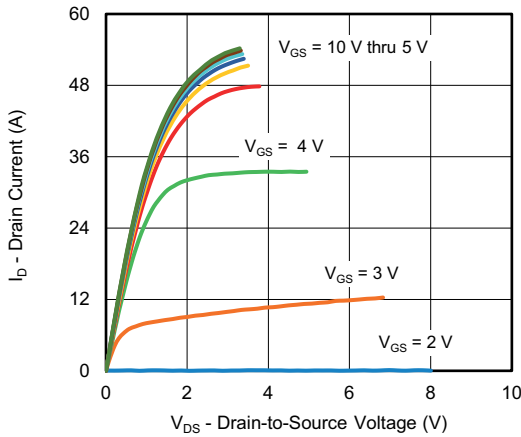
Notes

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing
c. Independent of operating temperature

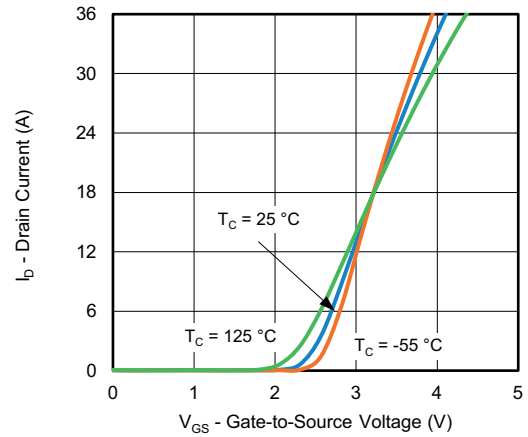
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



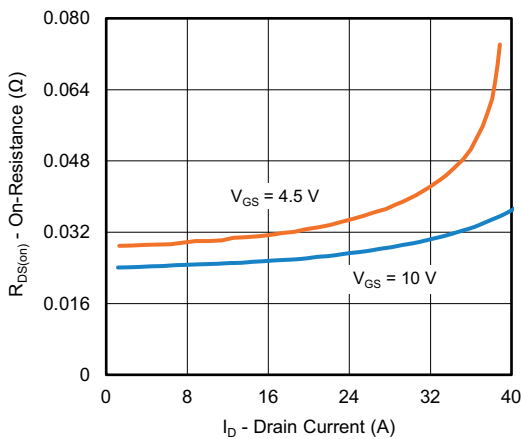
N-CHANNEL TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)



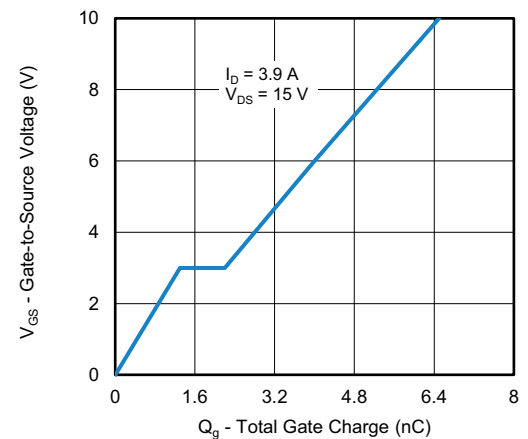
Output Characteristics



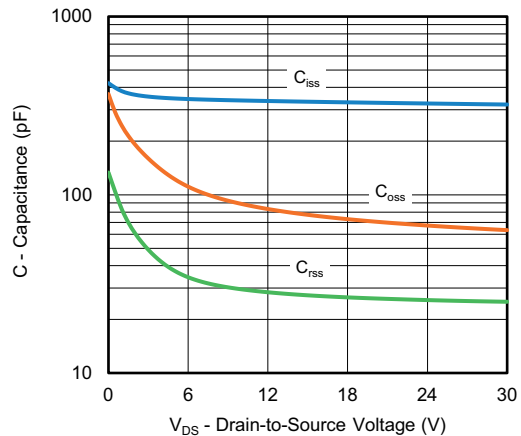
Transfer Characteristics



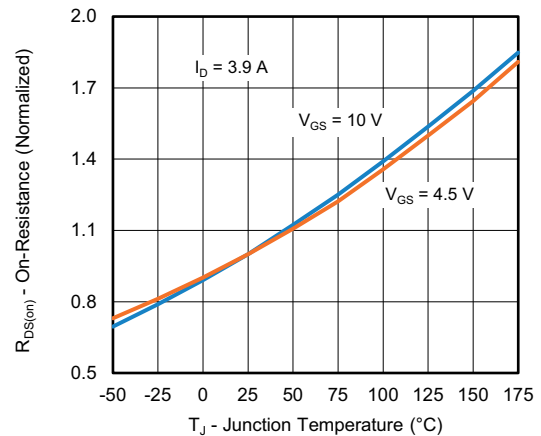
On-Resistance vs. Drain Current



Gate Charge



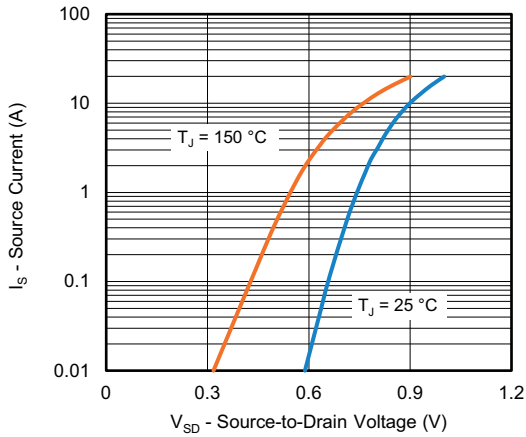
Capacitance



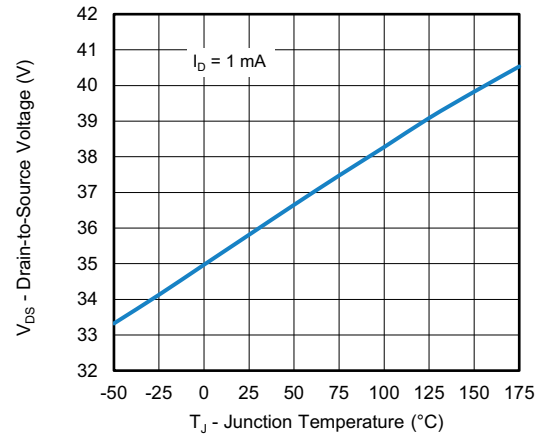
On-Resistance vs. Junction Temperature



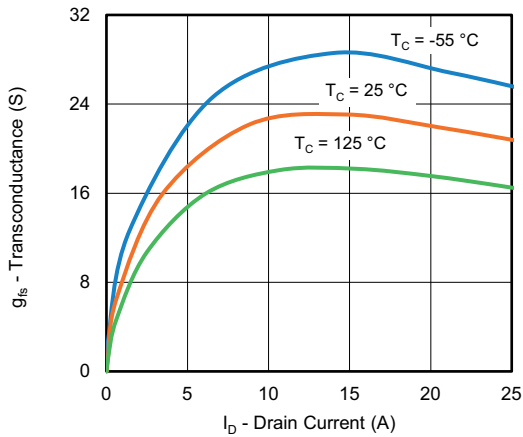
N-CHANNEL TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



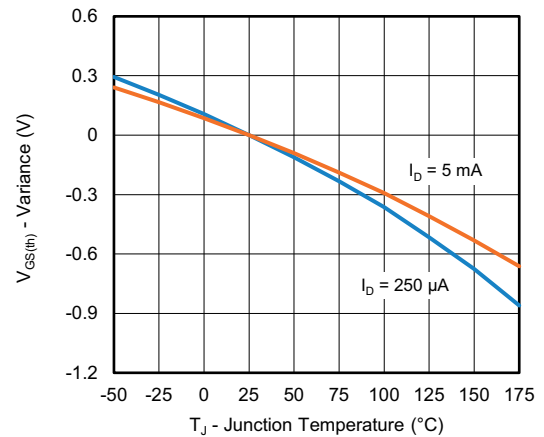
Source Drain Diode Forward Voltage



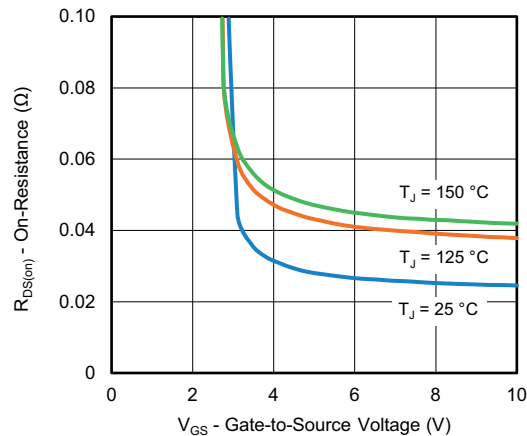
Drain Source Breakdown vs. Junction Temperature



Transconductance



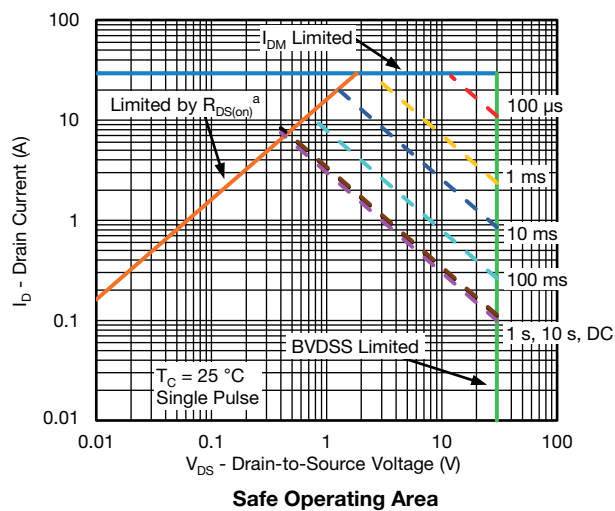
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



N-CHANNEL THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

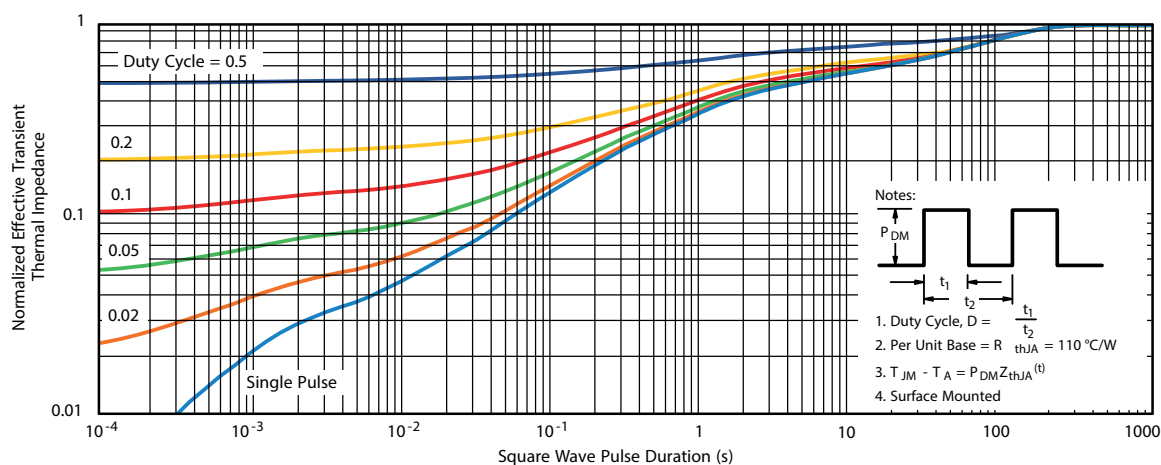


Note

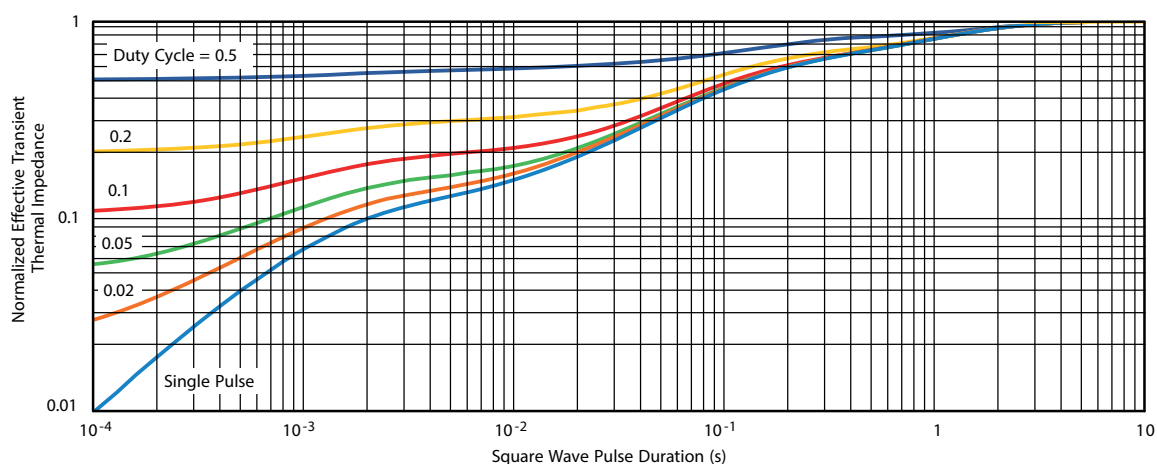
- a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



N-CHANNEL THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



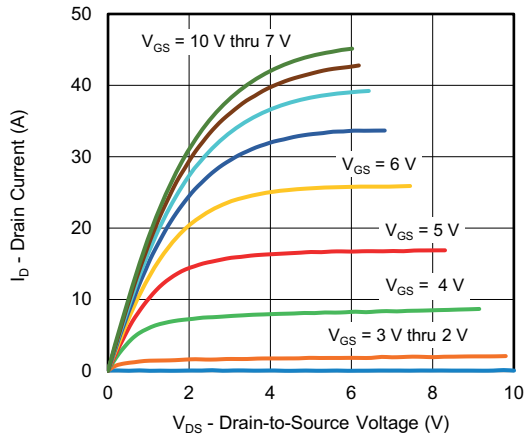
Normalized Thermal Transient Impedance, Junction-to-Foot

Note

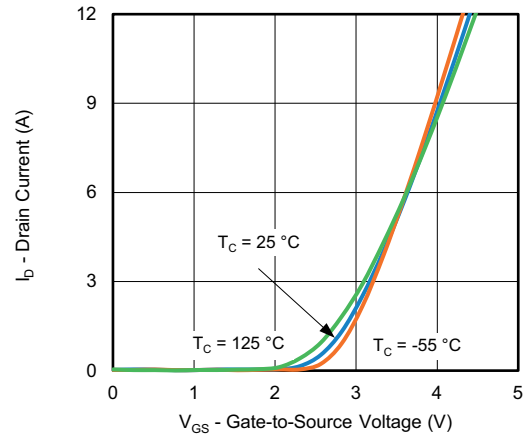
- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^{\circ}\text{C}$)are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



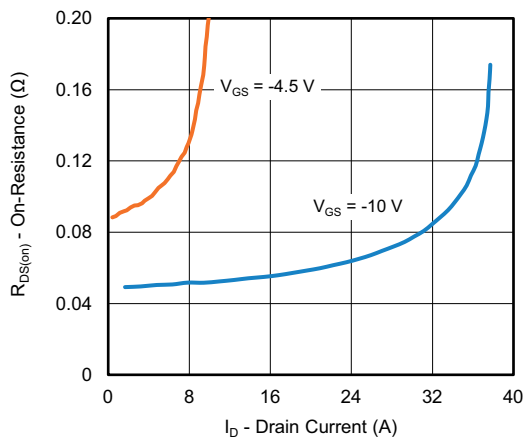
P-CHANNEL TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)



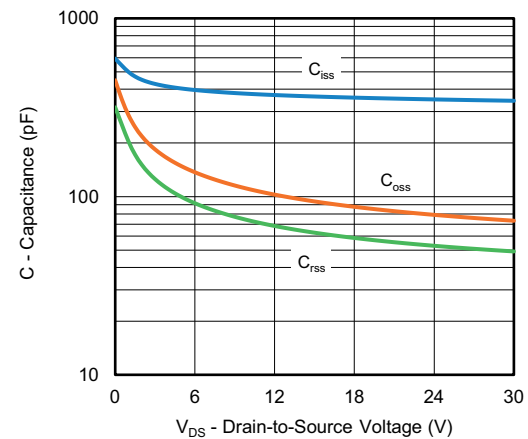
Output Characteristics



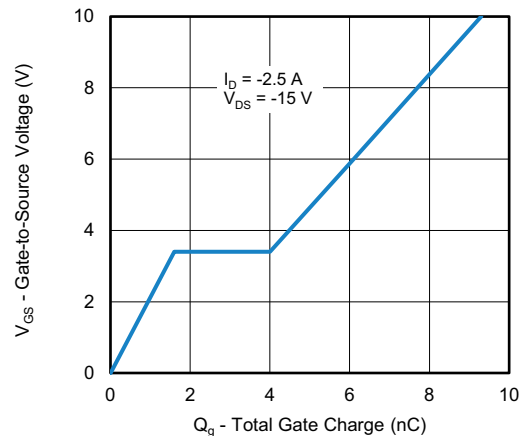
Transfer Characteristics



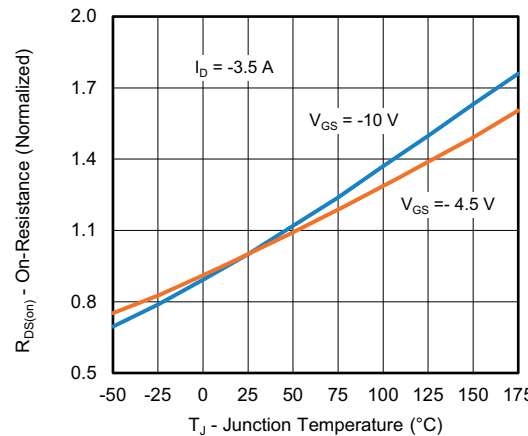
On-Resistance vs. Drain Current



Capacitance



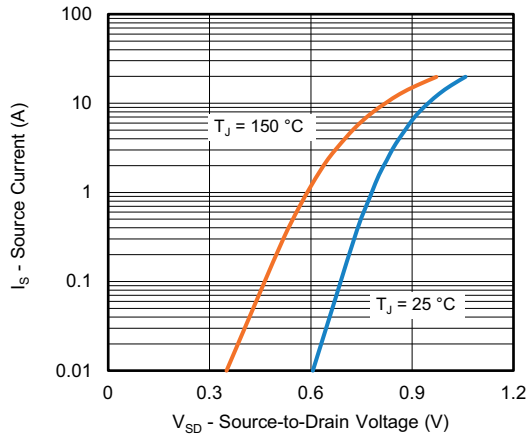
Gate Charge



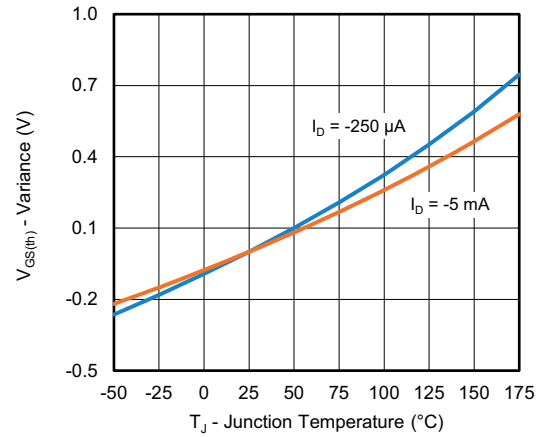
On-Resistance vs. Junction Temperature



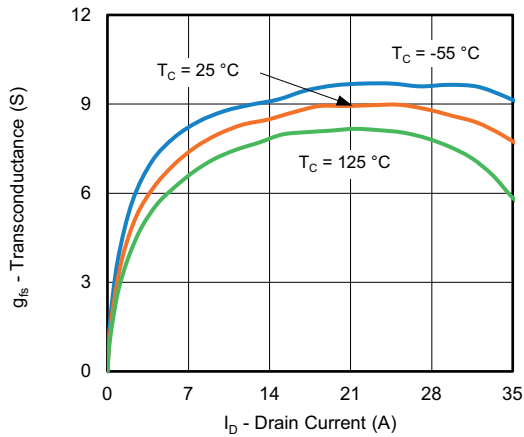
P-CHANNEL TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



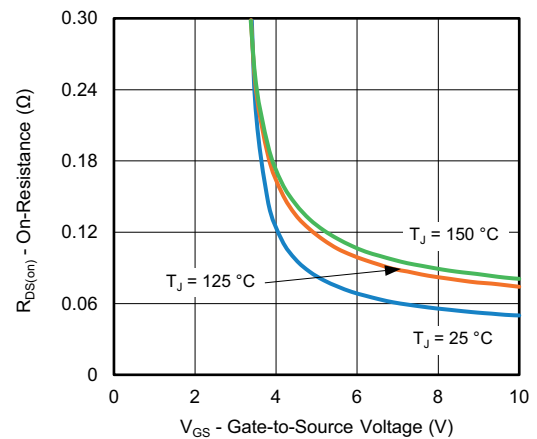
Source Drain Diode Forward Voltage



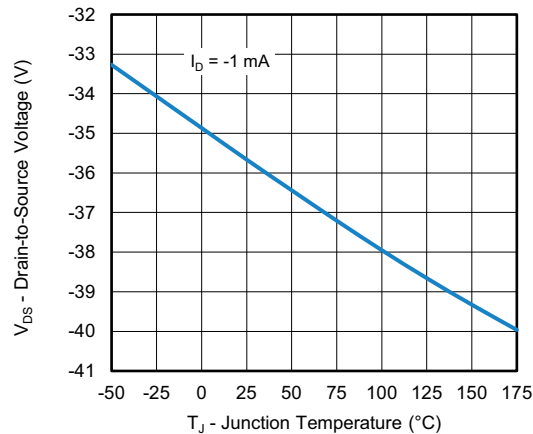
Threshold Voltage



Transconductance



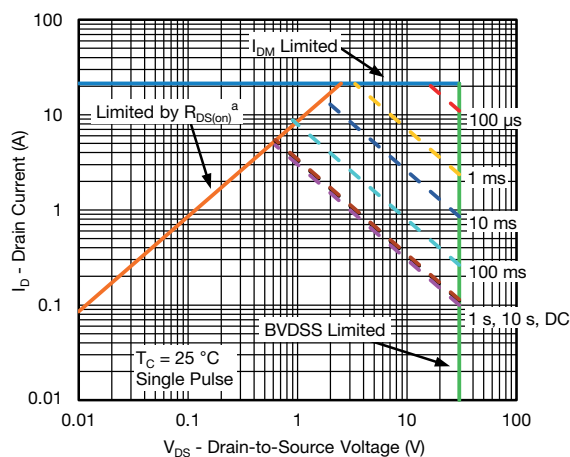
On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature



P-CHANNEL THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



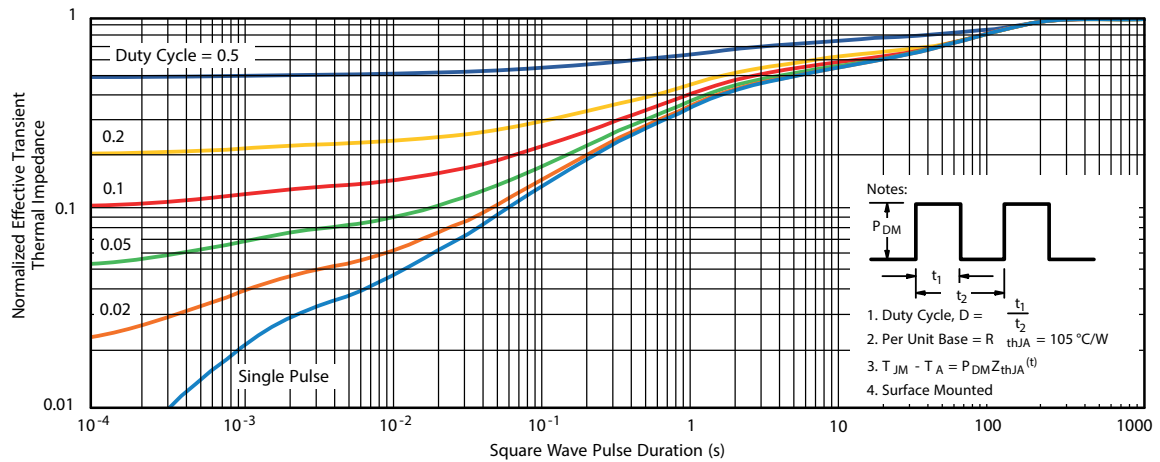
Safe Operating Area

Note

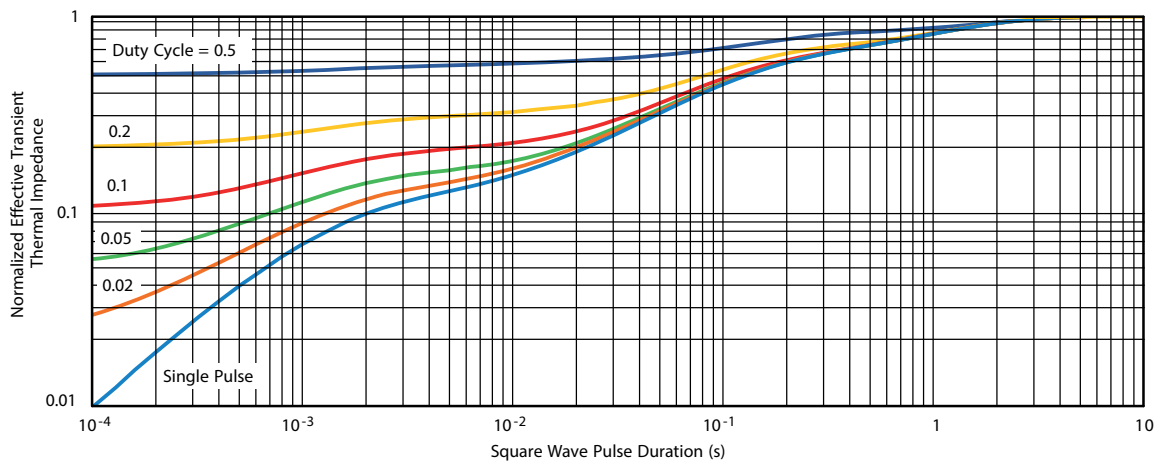
- a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



P-CHANNEL THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Case ($25\text{ }^{\circ}\text{C}$)
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Vishay Material Code	Customer Material	Location
SQ4532AEY-T1_BE3	SLNSQ4532AEY-T1-BE3	Ft Worth